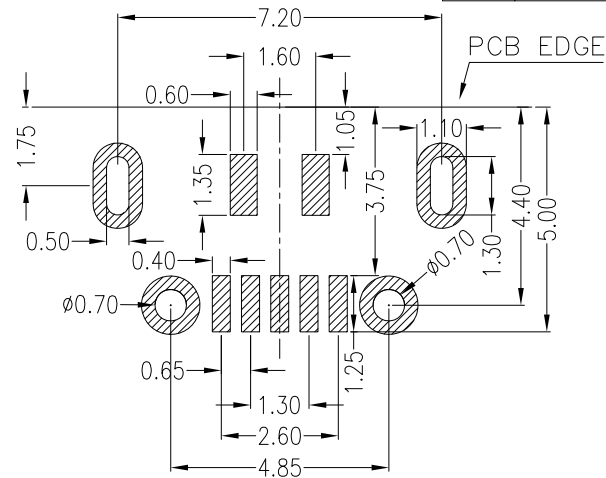
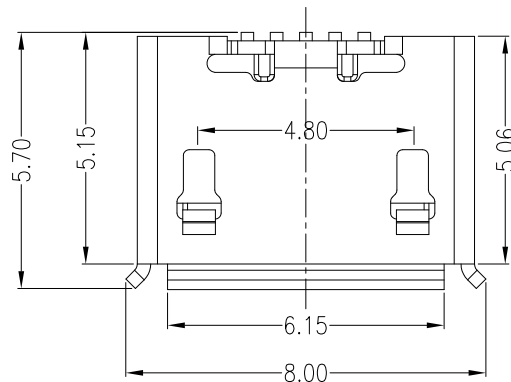
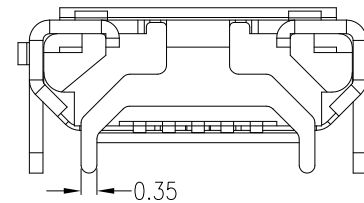
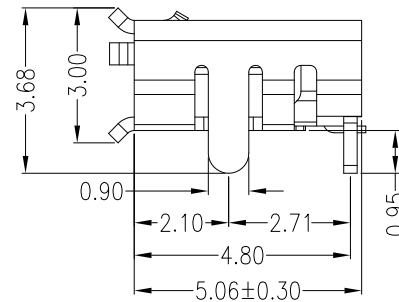
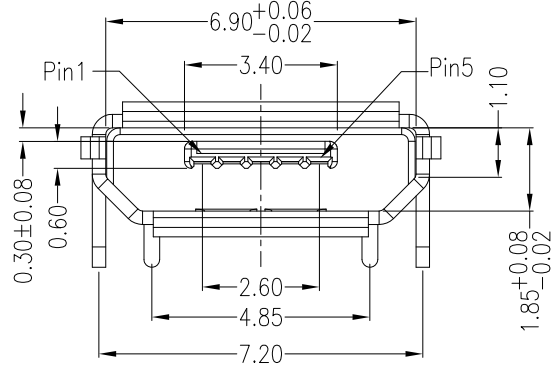


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2017/06/12	Phebe Su
A1			Change shell material	2018/01/02	Phebe Su



PCB 图仅供参考



NOTES:

1.MATERIAL:

- 1.1 HOUSING: HIGH TEMPERATURE PLASTIC, LCP BLACK
1.2 CONTACT: COPPER ALLOY. $t=0.15\text{mm}$
1.3 SHELL: SUS304, $t=0.30\text{mm}$

2.ELECTRICAL SPECIFICATION:

- 3.1 CURRENT RATING:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
3.2 VOLTAGE:30 VAC
3.3 TEMPERATURE RANGE:-40°C~85°C
3.4 CONTACT RESISTANCE:30 MILLIONHM MAX.
3.5 DIELECTRIC WITHSTANDING VOLTAGE:100 V(ac) for 1 min.
3.6 INSULATION RESISTNACE:100 MEGOHMS MIN

3.MECHANICAL SPECIFICATION:

MATING FORCE:35N MAX
UNMATING FORCE:8N MIN
DURABILITY:5000 CYCLES

MATRIX PART NO:

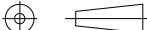
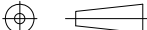
MUSB 05 - 01 - 285

Matrix-USB—

Pin number—

—Series Number

- Gold Plating:
 - 01=1u"
 - 03=3u"
 - 30=30u"

NO	VARIETY	QTY	MATERIAL	REMARK	
 Matrix Electronics Co.,Ltd					
TOLERANCE: X: X.X ±0.15 X.XX ±0.10 X.XXX ±0.05 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2018/01/02	PART NAME: MICRO USB B/F SMD	
		CHECKED BY: Vicky Hsieh	DATE : 2018/01/02	PART NO.	MUSB05-01-285
		APPROVED BY1: Richard Hsieh	DATE : 2018/01/02	MOLD NO.	NA
UNIT: mm [inch]		APPROVED BY2: Richard Hsieh	DATE :	DRAW NO.	
SCALE:1:1	SIZE:A4		2018/01/02	SHEET NO.	1 OF 1